

**Amendments to the Abstract**

Please replace the Abstract with the following amended Abstract:

A method for forming device packages includes forming a perimeter ~~comprising~~ with a reactive foil and a bonding material interposed between a first wafer and a second wafer, pressing the first and the second wafers against the reactive foil and the bonding material, initiating the reactive foil, wherein the reactive foil ~~heating~~ heats the bonding material to create a bond between the first and the second wafers, and singulating the first and the second wafers into the device packages.